

## CALENDAR

Upcoming: March 4–6 Advanced Packaging Materials; March 12–13 Biomaterials; March 14–15 Proteomics—The New Frontier; and April 1–5 MRS Spring Meeting, MRS.

To list an event in the Calendar, contact J. Meiksin, Materials Research Society, 506 Keystone Drive, Warrendale, PA 15086-7573; 724-779-3004 ext. 522; fax 724-779-8313; bulletin@mrs.org.

MRS, A-MRS, C-MRS, E-MRS, MRS-A, MRS-I, MRS-J, MRS-K, MRS-R, MRS-S, MRS-T, M-MRS, or IUMRS at the end of an entry indicates sponsorship or co-sponsorship of an event by the International Union of Materials Research Societies or one of its adhering bodies. "Endorsed" identifies events endorsed by MRS.

▼ identifies a new or revised entry this month.

See the November 2001 MRS BULLETIN for January 2002 Calendar entries.

## FEBRUARY 2002

1–3 Intl. Conf. on Advances in Materials and Materials Processing, *Kharagpur, India*. Dept. of Metallurgical and Materials Engineering, Indian Inst. of Technology, Kharagpur 721 302, India; 91-3222-82280; fax 91-3222-55303; e-mail icamp@metal.iitkgp.ernet.in.

3–6 OSA Meeting on Advanced Solid-State Lasers, *Québec City, Canada*. Optical Society of America, Conf. Services Dept., 2010 Massachusetts Ave., NW, Washington, DC 20036-1023; 202-416-1907; fax 202-416-6140; e-mail cust.serv@osa.org; www.osa.org/mtg\_conf.

7–10 OSA Meeting on Laser Applications to Chemical and Environmental Analysis, *Boulder, CO*. Optical Society of America, Conf. Services Dept., 2010 Massachusetts Ave., NW, Washington, DC 20036-1023; 202-416-1907; fax 202-416-6140; e-mail cust.serv@osa.org; www.osa.org/mtg\_conf.

17–21 TMS Annual Meeting, *Seattle, WA*. TMS, 184 Thorn Hill Rd., Warrendale, PA 15086; 724-776-9000; fax 724-776-3770; e-mail weissp@tms.org; www.tms.org/meetings.

20–22 ▼ Energy Efficient Lighting Systems—The Global Summit for Innovative and Market-Expanding Light Technologies, *Tucson, AZ*. Intertech Conferences, 19 Northbrook Office Park, Portland, ME 04105; 207-781-9800; fax 207-781-2150; e-mail info@intertechusa.com; www.intertechusa.com.

## MARCH 2002

2–3 Conf. on Film Formation: Mechanism, Properties, and Characterization, *Hilton Head, SC*. Inst. of Materials Science, Div. of Program Organization, P.O. Box 369, New Paltz, NY 12561; 914-255-0757; fax 914-255-0978; e-mail info@ims-np.org; http://ims-np.org.

2–3 Conf. on Polymer Degradation and Stabilization, *Hilton Head, SC*. Inst. of Materials Science, Div. of Program Organization, P.O. Box 369, New Paltz, NY 12561; 914-255-0757; fax 914-255-0978; e-mail info@ims-np.org; http://ims-np.org.

3–8 ▼ Biomimetic Engineering Conf., *Sandestin, FL*. United Engineering Foundation, 27th Floor, 3 Park Ave., New York, NY 10016-5902; 212-591-7836; fax 212-591-7441; e-mail engfnd@aol.com; www.engfnd.org.

3–8 ▼ Microlithography Conf., *Santa Clara, CA*. SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; www.spie.org.

4–6 4th Biennial Conf. on Polymer Stabilizers and Modifiers, *Hilton Head, SC*. Inst. of Materials Science, Div. of Program Organization, P.O. Box 369, New Paltz, NY 12561; 914-255-0757; fax 914-255-0978; e-mail info@ims-np.org; http://ims-np.org.

4–6 Advanced Packaging Materials—Processes, Properties and Interfaces, *Stone Mountain, GA*. Dr. Jianmin Qu, tel. 404-894-5687; e-mail jianmin.qu@me.gatech.edu; http://www.prc.gatech.edu/conferences/materials2002. Endorsed.

4–6 Conf. on Film Formation: Science and Technology, *Hilton Head, SC*. Inst. of Materials Science, Div. of Program Organization, P.O. Box 369, New Paltz, NY 12561; 914-255-0757; fax 914-255-0978; e-mail info@ims-np.org; http://ims-np.org.

4–7 Manufacturing Applications Expo Intl.: AWS Welding Show and PMA METALFORM Expo, *Chicago, IL*. American Welding Society, 550 NW LeJeune Rd., Miami, FL 33126; 800-443-9353; fax 305-443-7559; e-mail www.aws.org; www.maxinternational.com.

7–8 Conf. on Advanced Microelectronic Manufacturing and Nanotechnologies, *Santa Clara, CA*. SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; www.spie.org.

11–13 IMAPS Intl. Conf. on Advanced Packaging and Systems, *Reno, NV*. Intl. Microelectronics and Packaging Society, 611 2nd St. N.E., Washington, DC 20002; 202-548-4001; fax 202-548-6115; www.imaps.org.

11–13 Intl. Conf. on High-Performance Structures and Composites, *Seville, Spain*. Conf. Secretariat, HPCS 2002, Wessex Inst. of Technology, Ashurst Lodge, Ashurst, Southampton, SO40 7AA, UK; 44-2380-293223; fax 44-2380-292853; e-mail shanley@wessex.ac.uk; www.wessex.ac.uk/conferences/2002/hps02.

11–15 3rd Intl. Conf. on Porous Semiconductors—Science and Technology, *Tenerife, Spain*. E. Matveeva (PSST-2002), Dept. de Ingeniería Mecánica y de Materiales, Univ. Politécnica de Valencia, Camino de Vera s/n, 46022 Valencia, Spain; 34-96-387-7620; fax 34-96-387-7629; e-mail psst-2002@upvnet.upv.es; www.upv.es/psst\_2002.

12–13 ▼ Biomaterials—The Next Frontiers: Biomedical, Bioelectronic, Biomaterialization, Bioanalytical, *Newark, Delaware*. Kathleen C. Werrell, Assistant Dean, Engineering Outreach, University of Delaware, Newark, DE 19716-3101; tel. 302-831-4863; fax 302-831-8179; email enggoutreach@udel.edu; www.udel.edu/engg/outreach/Biomaterials.htm. Endorsed.

12–14 Chemtex and Corrosion Conf., *Dubai, United Arab Emirates*. Intl. Expo-Consults L.L.C., P.O. Box 50006, Dubai, United Arab Emirates; 971-4-3435777; fax 971-4-3436115; e-mail iec@emirates.net.ae; www.expo-consults.com.

14–15 ▼ Proteomics—The New Frontier, *Newark, Delaware*. Kathleen C. Werrell, Assistant Dean, Engineering Outreach, University of Delaware, Newark, DE 19716-3101; tel. 302-831-4863; fax 302-831-8179; email enggoutreach@udel.edu; www.udel.edu/engg/outreach/Proteomics.htm. Endorsed.

17–20 7th Intl. Multidisciplinary Conf. on Complexity and Fractals in the Sciences, *Granada, Spain*. M.M. Novak, School of Mathematics, Kingston Univ., Penrhyn Rd., Surrey KT1 2EE, UK; www.kingston.ac.uk/fractal.

17–21 Conf. on Smart Structures and Materials, *San Diego, CA*. SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; www.spie.org.

18–22 APS March Meeting, *Indianapolis, IN*. American Physical Society, One Physics Ellipse, College Park, MD 20740-3844; 301-209-3200; fax 301-209-0865; e-mail meetings@aps.org; www.aps.org.

18–22 Intl. Solvent Extraction Conf., *Cape Town, South Africa*. Conf. Secretariat, Private Bag X3015, Randburg 2125, South Africa; 27-11-709-4255; fax 27-11-709-4326; e-mail isec2002@mintek.co.za; www.isec2002.org.za.

25–29 ▼ Conf. on Bulk Metallic Glasses, *Keelung, Taiwan*. United Engineering Foundation, 27th Floor, 3 Park Ave., New York, NY 10016-5902; 212-591-7836; fax 212-591-7441; e-mail engfnd@aol.com; www.engfnd.org.

26–28 ▼ 9th Intl. Conf. on Fiber-Reinforced Composites, *Univ. of Newcastle upon Tyne, UK*. L. Blackburn; 44-191-284-7590; e-mail louise.blackburn@btinternet.com.

27–28 Forum on Materials and Society: From Research to Manufacturing; *Washington, DC*. Natl. Materials Advisory Board, 2101 Constitution Ave. N.W., Harris Bldg., Rm. 262, Washington, DC 20007; 202-334-3505; fax 202-334-3718; e-mail nmab@nas.edu; www4.nas.edu.

## APRIL 2002

1–5 MRS Spring Meeting, *San Francisco, CA*. Materials Research Society, 506 Keystone Dr., Warrendale, PA 15086-7573; 724-779-3003; fax 724-779-8313; e-mail info@mrs.org; www.mrs.org. MRS.

3–4 ▼ Cool Chips Conf., *Monterey, CA*. C. Spear, Intertech Conferences, 19 Northbrook Office Park, Portland, ME 04105; 207-781-9612; fax 207-781-2150; e-mail chuck@intertechusa.com; www.intertechusa.com.

3–5 Intl. Conf. on High-Density Interconnect and Systems Packaging, *Santa Clara, CA*. Intl. Microelectronics And Packaging Society, 611 2nd St. NE, Washington, DC 20002; 202-548-4001; fax 202-548-6115; www.imaps.org.

8–10 Intl. Conf. on Metal Powder Deposition for Rapid Manufacturing, *San Antonio, TX*. S.E. Leatherman, Technical Programs Mgr., Metal Powder Industries Federation, 105 College Rd. East, Princeton, NJ 08540-6692; 609-452-7700; fax 609-987-8523; e-mail leatherm@mpif.org; www.mpif.org.

9–11 Materials Congress 2002, *London, UK*. V. Morrison, IOM Communications, 1 Carlton House Terrace, London SW1Y 5DB, UK; 44-20-7451-7340; fax 44-20-7839-2289; www.materials.org.uk/congress2002/intro.htm.

11–12 ▼ 27th AAAS Colloquium on Science and Technology Policy, *Washington, DC*. American Assoc. for the Advancement of Science, Science and Policy Programs, 1200 New York Ave. N.W., Washington, DC 20005; 202-326-6600; fax 202-289-4950; e-mail slita@aaas.org; www.aaas.org/spp/dspp/rd/colloqu.htm.

13–18 ▼ 15th Intl. Symposium on Microscale Separations and Analysis, *Stockholm, Sweden*. HPCE 2002 Secretariat, The Swedish Chemical Society, Wallingatan 24, SE-111 24 Stockholm, Sweden; 46-8-411-5260; fax 46-8-10-66-78; e-mail monika@chemsoc.se.; www.chemsoc.se/sidor/KK/hpce2002/hpce2002.htm.

13–18 45th SVC Technical Conf., *Lake Buena Vista, FL*. Society of Vacuum Coaters, 71 Pinon Hill Place N.E., Albuquerque, NM 87122-1914; 505-856-7188; fax 505-856-6716; e-mail svcinfo@svc.org; www.svc.org.

14–17 ▼ 5th Conf. on Material Forming, *Krakow, Poland*. H. Kusiak, Dept. of Computational Methods in Metallurgy, Akademia Górniczo-Hutnicza, Mickiewiczza 30, 30-059 Krakow, Poland; 48-12-617-2921; e-mail hkusiak@metal.agh.edu.pl.

17–19 IMAPS Intl. Conf. on Electronics Packaging and 16th Microelectronics Show, *Tokyo, Japan*. Intl. Microelectronics and Packaging Society, 611 2nd St. N.E., Washington, DC 20002; 202-548-4001; fax 202-548-6115; www.imaps.org.

## MAY 2002

**20-23** APS April Meeting, *Albuquerque, NM*. American Physical Society, 1 Physics Ellipse, College Park, MD 20740-3844; 301-209-3200; fax 301-209-0865; e-mail meetings@aps.org; www.aps.org.

**21-26** ▼ Conf. on High-Power Laser Ablation, *Taos, NM*. SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; www.spie.org.

**22-25** Intl. Conf. on Computational Nano Science, and Modeling and Simulation of Microsystems, *San Juan, Puerto Rico*. ICCN-MSM, 696 San Ramon Valley Blvd., Ste. 423, Danville, CA 94526-4022; 925-743-9466; fax 509-696-6416; e-mail wenning@cr.org; www.cr.org/MSM2002/register.html.

**28-1** 104th ACeRS Annual Meeting, *St. Louis, MO*. The American Ceramic Society, P.O. Box 6136, Westerville, OH 43086-6136; 614-890-4700; fax 614-899-6109; e-mail info@acers.org; www.ceramics.org.

**28-2** ▼ Intermag Europe Conf. of the IEEE Magnetics Society, *Amsterdam, The Netherlands*. Intermag Europe 2002, Courtesy Associates, 2025 M St. N.W., Ste. 800, Washington, DC 20036; 202-973-8676; fax 202-973-8722; e-mail intermag@courtesyassoc.com; www.intermagconference.com.

**28-3** ▼ Conf. on High-Performance Powder Metallurgy Components, *Coimbra, Portugal*. United Engineering Foundation, 27th Floor, 3 Park Ave., New York, NY 10016-5902; 212-591-7836; fax 212-591-7441; e-mail engfnd@aol.com; www.engfnd.org.

**29-30** IMAPS Technology Workshop on Ceramic Applications for Microwave and Photonic Packaging, *Providence, RI*. Intl. Microelectronics and Packaging Society, 611 2nd St. N.E., Washington, DC 20002; 202-548-4001; fax 202-548-6115; www.imaps.org.

**29-2** Intl. Conf. on Characterization and Metrology for ULSI Technology, *Gaithersburg, MD*. L. Printz, NIST, Gaithersburg, MD 20899; e-mail lori.printz@nist.gov; www.eeel.nist.gov/812/conference. **Endorsed.**

**5-8** 8th Magneto-Optical Recording Intl. Symposium, *Bénodet, Brittany, France*. MORIS'2002 Secretariat, c/o N. Keller, LMOV—Univ. of Versailles/CNRS, 45 Ave. des Etats-Unis, 78035 Versailles Cedex, France; 33-139-25-4670; fax 33-139-25-4652; e-mail moris2002@physique.uvsq.fr; www.univ-brest.fr/moris2002.

**6-7** Intl. Conf. on Functionally Graded Materials, *Denver, CO*. S. Leatherman, Technical Programs Mgr., Metal Power Industries Federation, 105 College Rd. East, Princeton, NJ 08540-6692; 609-452-7700; fax 609-987-8523; e-mail leatherm@mpif.org; www.mpif.org.

**12-16** SAMPE Conf. on Affordable Material Technology—Platform to Global Value and Performance, *Long Beach, CA*. D. Weaver, SAMPE Business Office, P.O. Box 2459, Covina, CA 91722; 626-331-0616; fax 626-332-8929; e-mail dweaveribo@cs.com; www.sampe.org.

**12-17** 201st Meeting of the Electrochemical Society, *Philadelphia, PA*. The Electrochemical Society, 65 S. Main St., Pennington, NJ 08534-2839; 609-737-1902; fax 609-737-2743; e-mail ecs@electrochem.org; www.electrochem.org.

**19-23** ▼ 11th Intl. Conf. on Electron Microscopy of Solids, *Krynica, Poland*. Polish Academy of Sciences, Inst. of Metallurgy and Materials Science, 30-059 Cracow, Reymonta St. 25, Poland; fax 48-12-637-2192; e-mail emc2002@imim-pan.krakow.pl; www.imim-pan.krakow.pl/emc2002.

**20-23** ▼ European Workshop on Smart Structures in Engineering and Technology, *Giens, France*. A. Mitchell, Workshop Secretary, Univ. of Strathclyde, Dept. of Electronic and Electrical Engineering, 204 Royal College Bldg., George St., Glasgow, G1 1XW, UK; 44-141-548-2543; fax 44-141-553-1955; e-mail a.mitchell@eee.strath.ac.uk; www.asstnet.org.

**22-25** Intl. Conf. on Nuclear Structure: Mapping the Triangle, *Grand Teton Natl. Park, WY*. L. Riedinger, Oak Ridge Natl. Lab.; 865-574-4321; fax 865-574-8225; e-mail triangle@ornl.gov; http://wnsl.physics.yale.edu/icns2002.

**24-28** APS Div. of Particles and Fields Meeting, *Williamsburg, VA*. DPF2002, Dept. of Physics, College of William and Mary, Williamsburg, VA 23187-8795; 757-221-3538; fax 757-221-3540; e-mail dpf2002@physics.wm.edu; http://www.dpf2002.org.

**25-26** ▼ Conf. on Synchrotron Radiation: Earth, Environmental, and Materials Sciences Applications, *Saskatoon, Saskatchewan, Canada*. G.S. Henderson, Mineralogical Assoc. of Canada, P.O. Box 78087, 1460 Merivale Rd., Ottawa, Ontario K2E 1B1, Canada; phone and fax 613-226-4651; e-mail henders@geology.utoronto.ca; www.mineralogicalassociation.ca.

**25-30** ▼ American Crystallographic Assoc. Annual Meeting, *San Antonio, TX*. American Crystallographic Assoc., P.O. Box 96 Ellicott Station, Buffalo, NY 14205-0096; 716-856-9600; fax 716-852-4846; e-mail aca@hwi.buffalo.edu; www.hwi.buffalo.edu/aca/.

**27-29** 7th European Symposium on Polymer Blends, *Lyon-Villeurbanne, France*. Secretariat, 7th European Symposium on Polymer Blends, Lab. des Matériaux Macromoléculaires, Bat J. Verne, INSA Lyon, 20 Ave. Albert Einstein, 69621, Villeurbanne Cedex, France; 33-4-72-43-8527; e-mail polymerblends@insa-lyon.fr; www.insa-lyon.fr/polymer\_blends/index.htm.

**27-31** ▼ Intl. Congress on Laser Advanced Materials Processing, *Osaka, Japan*. SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; www.spie.org.

## JUNE 2002

**2-6** ▼ Intl. Conf. on Applications of Photonic Technology, *Quebec City, Canada*. SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; www.spie.org.

**3-7** 9th Intl. Conf. on Muon Spin Rotation, Relaxation, and Resonance, *Williamsburg, VA*. C.E. Stronach, Conf. Chair, Physics Dept., P.O. Box 9325, Virginia State Univ., Petersburg, VA 23806; 804-524-5915; fax 804-524-5439; e-mail cstronac@vsu.edu; http://muon.physics.wm.edu/~musr2002.

**3-7** ▼ 11th Intl. Conf. on Metal Organic Vapor Phase Epitaxy, *Berlin, Germany*. IC MOVPE XI Conf. Office, TU Berlin Servicegesellschaft mbH, c/o Technische Univ. Berlin, Steinplatz 1, D-10623 Berlin, Germany; fax 49-30-314-24087; e-mail office@icmovpe-2002.de; www.icmovpe-2002.de.

**5-8** ▼ 4th Intl. Conf. on Mechanics and Materials in Design, *Nagoya, Japan*. H. Fujii, Dept. of Mechanical Engineering, Gifu Univ., Japan; e-mail fujiih@mech.gifu-u.ac.jp.

**8-13** ▼ 39th Clay Minerals Society Annual Meeting, *Boulder, CO*. K. Nagy, Dept. of Geological Sciences, Univ. of Colorado, Boulder, CO 80309; 303-492-6187; fax 303-492-2602; e-mail kathryn.nagy@colorado.edu; www.colorado.edu/geolsci/cms/.

**9-13** ▼ Conf. on Nanostructured Advanced Magnetic Materials, *Irsee, Germany*. United Engineering Foundation, 27th Floor, 3 Park Ave., New York, NY 10016-5902; 212-591-7836; fax 212-591-7441; e-mail engfnd@aol.com; www.engfnd.org.

**10-12** ▼ 4th Intl. Conf. on Materials for Microelectronics and Nanoengineering, *Espoo, Finland*. L. Bromley, Conferences and Events, IOM Communications; 44-20-7451-7302; fax 44-20-7839-2289; e-mail lisa\_bromley@materials.org.uk.

**10-14** 8th Intl. Conf. on Electronic Materials, *Xi'an, China*. J. Cheng; 86-10-6894-4280; fax 86-10-6842-8640; e-mail cmrssec@public.bta.net.cn; www.c-mrs.org.cn/icem2002. **C-MRS.**

**16-18** European IMAPS Symposium, *Cracow, Poland*. Intl. Microelectronics And Packaging Society, 611 2nd St. NE, Washington, DC 20002; 202-548-4001; fax 202-548-6115; www.imaps.org.

**16-20** Intl. Cryogenic Materials Conf., *Xi'an, China*. Y. Feng, Northwest Inst. for Non-ferrous Metal Research, P.O. Box 51, Xi'an, Shaanxi 710016, China; 86-29-623-1079; fax 86-29-623-1103; e-mail smrc@pub.xaonline.com.

**16-21** ▼ 6th Intl. Conf. on Nanostructured Materials, *Orlando, FL*. K. Finnerty, Conf. Secretary, Dept. of Ceramic and Materials Engineering, Rutgers Univ., 607 Taylor Rd., Piscataway, NJ 08854; 732-445-2245; fax 732-445-5977; e-mail kfinnert@rci.rutgers.edu; www.nano2002.com.

**16-21** Powder Metallurgy and Particulate Materials World Congress, *Orlando, FL*. S. Leatherman, Metal Powder Industries Federation, 105 College Rd. East, Princeton, NJ 08540-6692; 609-452-7700; fax 609-987-8523; e-mail leatherm@mpif.org; www.mpif.org.

**17-20** 1st Intl. Conf. on Multiscale Materials Modeling, *London, UK*. MMM Local Organising Committee, Dept. of Materials, Queen Mary, Univ. of London, London E1 4NS, UK; 44-20-7882-5159; fax 44-20-8981-9804; e-mail x.guo@qmw.ac.uk; www.multiscalemodelling.com.

**18-21** E-MRS Spring Meeting, *Strasbourg, France*. E-MRS, 23 rue du Loess, B.P. 20, 67037 Strasbourg Cedex 02, France; 33-3-8810-6372; fax 33-3-8810-6343; e-mail emrs@phase.c-strasbourg.fr; www-emrs.c-strasbourg.fr. **E-MRS.**

**19-21** ▼ 5th European Workshop on Low-Temperature Electronics, *Grenoble, France*. WOLTE-5, LPCS-IMEP, ENSERG, B.P. 257, 38016 Grenoble Cedex 1, France; fax 33-4-76-85-60-70; e-mail balestra@enserg.fr.

**22-28** ▼ Intl. Quantum Electronics Conf., collocated with Conf. on Lasers, Applications, and Technologies, *Moscow, Russia*. SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; www.spie.org.

**23-26** Intl. Conf. on Thermomechanical Processing, *Sheffield, UK*. Thermomechanical Processing: Mechanics, Microstructure, and Control, c/o IMPETUS Admin. Office, Univ. of Sheffield, Sir Frederick Mappin Bldg., Mappin St., Sheffield S1 3JD, UK; 44-114-222-6018; fax 44-114-222-6015; e-mail tpmmc@sheffield.ac.uk; http://dyn052176.shef.ac.uk/conference\_2002.

**23-27** 6th Intl. Conf. on Computer Simulation of Radiation Effects in Solids, *Dresden, Germany*. COSIRES2002, c/o Forschungszentrum Rossendorf e.V., Inst. of Ion Beam Physics and Materials Research, P.O. Box 510119, 01314 Dresden, Germany; fax 48-351-260-3285; e-mail COSIRES2002@fz-rossendorf.de; www.fz-rossendorf.de/FWI/COSIRES2002.

**23-28** 11th Intl. Meeting on Lithium Batteries, *Monterey, CA*. IMLB 11 Conf. Secretariat, c/o The Electrochemical Society, Inc., 65 S. Main St., Pennington, NJ 08534-2839; 609-737-1902; fax 609-737-2743; e-mail ecs@electrochem.org; www.electrochem.org/meetings/011/imlb11.html.

**24-27** ▼ Natl. Space and Missile Materials Symposium, *Colorado Springs, CO*. NSMMS, Anteon Corp., 5100 Springfield St., Ste. 509, Dayton, OH 45431-1264; fax 937-253-2296; e-mail mkubal@anteon.com; www.usasymposium.com.

**26-28** Electronic Materials Conf., *Santa Barbara, CA*. TMS Meetings Services, 184 Thorn Hill Rd., Warrendale, PA 15086; 724-776-9000; fax 724-776-3770; e-mail mtgserv@tms.org; www.tms.org/meetings.

## JULY 2002

**1-5** Conf. on Coatings Science and Technology, *Athens, Greece*. Inst. of Materials Science, Div. of Program Organization, P.O. Box 369, New Paltz, NY 12561; 914-255-0757; fax 914-255-0978; e-mail info@ims-np.org; http://ims-np.org.

**1-5** Intl. Conf. on Fuel Cells, *Lucerne, Switzerland*. European Fuel Cell Forum, P.O. Box 99, CH-5452 Oberrohrdorf, Switzerland; 41-56-496-7292; fax 41-56-496-4412; e-mail info@efcf.com; www.efcf.com.

**7-11** 47th Annual SPIE Meeting, *Seattle, WA*. SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; www.spie.org.

**7-12** 7th Intl. Workshop on Positron and Positronium Chemistry, *Knoxville, TN*. S. Lantz, PPC7, Oak Ridge Natl. Lab., P.O. Box 2008, M.S. 6142, Oak Ridge, TN 37831; 865-574-4882; fax 865-574-8363; e-mail Sharon.Lantz@ornl.gov; www.ornl.gov/ppc.

**8-12** 13th Intl. Conf. on Internal Friction and Ultrasonic Attenuation in Solids, and 1st Scientific Exhibition on Mechanical Spectroscopy Equipment, *Bilbao, Spain*. J. San Juan, Dept. Fisica de la Materia Condensada, Facultad de Ciencias, Univ. del Pais Vasco, UPV-EHU, Apdo. 644-48080, Bilbao, Spain; 34-94-601-2478; fax 34-94-464-8500; e-mail icifuas@lg.ehu.es; http://icifuas.ehu.es.

**11-12** Conf. on Industry-University Partnership in Materials Engineering, *London, UK*. D. Greenaway, Conf. and Events, IOM Communications; 44-20-7451-7324; fax 44-20-7839-2289; e-mail Doreen.Greenaway@materials.org.uk; www.materials.org.uk/iomevents/industry-univ/.

**14-18** 13th Intl. Symposium on Transport Phenomena, *Victoria, BC, Canada*. S. Dost, ISTEP-13, Dept. of Mechanical Engineering, Univ. of Victoria, Victoria, BC, Canada V8W 3P6; 250-721-8898; fax 250-721-6294; e-mail istp13@uvic.ca; www.istp13.uvic.ca.

**14-19** 10th Intl. Conf. on the Physics and Chemistry of Ice, *St. John's, Newfoundland, Canada*. Conf. Office, Rm. 315 Hatcher House, Memorial Univ. of Newfoundland, St. John's, NF Canada A1B 3P7; 709-737-7657; fax 709-737-3520; e-mail Stephen.Jones@nrc.ca; www.housing.mun.ca/conf/pci/.

**14-19** CIMTEC Intl. Conf. on Materials and Technologies: 10th Intl. Ceramics Congress and 3rd Forum on New Materials, *Florence, Italy*. CIMTEC 2002 Secretariat, P.O. Box 174, 48018 Faenza, Italy; 39-546-22461; fax 39-546-664138; www.dinamica.it/cimtec.

**14-19** Conf. on Polymer Colloids: Preparation and Properties of Aqueous Polymer Dispersions, *Irsee, Germany*. United Engineering Foundation, 3 Park Ave., New York, NY 10016-5902; 212-591-7836; fax 212-591-7441; e-mail engfnd@aol.com; www.uefoundation.org.

**14-25** 3rd Intl. Wilhelm and Else Heraeus Summerschool: Photonic Crystals, *Wittenberg, Germany*. R. Wehrspohn, Max-Planck Inst. für Mikrostrukturphysik, Weinberg 2, 06108 Halle, Saale, Germany; 49-345-558-2726; fax 49-345-551-1223; e-mail wehrspoh@mpi-halle.de; www.photonische-kristalle.de/summerschool.

**17-19** Intl. Conf. on Smart Materials, Structures, and Systems, *Bangalore, India*. SPIE, P.O. Box 10, Bellingham, WA 98227-0010; 360-676-3290; fax 360-647-1445; e-mail spie@spie.org; www.spie.org.

**21-26** 4th World Congress on Particle Technology, *Sydney, Australia*. J. Hatte, Conf. Coordinator, ICMS Australasia Pty Ltd., Level 6, 2 Bridge St., Sydney NSW 2000, Australia; 61-2-9241-1478; fax 61-2-9251-3552; e-mail josie@icmsaust.com.au; www.wcpt4.com/.

**21-26** 8th Intl. Conf. on New Diamond Science and Technology, *Melbourne, Australia*. B. Hewitt, Conf. Mgmt., Old Physics Bldg., Univ. of Melbourne, Parkville 3010, Victoria, Australia; 61-3-8344-6389; fax 61-3-8344-6122; e-mail icndst-8@unimelb.edu.au; www.conferences.unimelb.edu.au/icndst-8.

**22-25** Intl. Workshop on Nitride Semiconductors, *Aachen, Germany*. IWN 2002 Secretariat, Forschungszentrum Jülich GmbH, Conf. Service, 52425 Jülich, Germany; 49-24-6161-3833; fax 49-24-6161-5333; e-mail iwn2002@fz-juelich.de; www.fz-juelich.de/iwn2002.

**29-2** 26th Intl. Conf. on the Physics of Semiconductors, *Edinburgh, Scotland*. Conf. Dept., ICPS2002, Inst. of Physics, 76 Portland Place, London W1B 1NT, England; 44-20-7470-4800; fax 44-20-7470-4900; www.icps2002.org.

**29-2** 51st Denver X-Ray Conf., *Colorado Springs, CO*. D. Flaherty, Conf. Coordinator, Intl. Centre for Diffraction Data, 12 Campus Blvd., Newtown Square, PA 19073-3273; 610-325-9814; fax 610-325-9823; e-mail dxc@icdd.com; www.dxcicdd.com.

## AUGUST 2002

**1-2** Intl. Workshop on Processing and Applications of Superconductors, *Gatlinburg, TN*. Materials Research Society, 506 Keystone Dr., Warrendale, PA 15086-7573; 724-779-3003; fax 724-779-8313; e-mail info@mrs.org; www.mrs.org. **MRS.**

**4-8** 14th American Conf. on Crystal Growth and Epitaxy, *Seattle, WA*. T. Gentile, Conf. Secretariat, P.O. Box 3233, Thousand Oaks, CA 91359-0233; 805-492-7047; fax 805-492-4062; e-mail aacg@lafn.org; www.crystalgrowth.org.

**4-9** Applied Superconductivity Conf.®, *Houston, TX*. Centennial Conferences, 4800 Baseline Rd., Ste. A-112, Boulder, CO 80303; 303-499-2299; fax 303-499-2599; e-mail asc@centennialconferences.com; www.ascinc.org.

**18-23** Intl. Conf. on Electrophoretic Deposition: Fundamentals and Applications, *Banff, Canada*. United Engineering Foundation, 3 Park Ave., New York, NY 10016-5902; 212-591-7836; fax 212-591-7441; e-mail engfnd@aol.com; www.uefoundation.org.

**20-27** 23rd Intl. Conf. on Low-Temperature Physics, *Hiroshima, Japan*. Japan Convention Services, Inc., LT23, Nippon Press Ctr., Bldg., 2-2-1, Uchisaiwaicho, Chiyodaku, Tokyo 100-0011, Japan; 81-3-3508-1214; e-mail lt23@convention.co.jp; www.issp.u-tokyo.ac.jp/lt23.

**24-27** 3rd World Congress on Emulsions, *Lyon, France*. CME, 50 place Marcel Pagnol, 92100 Boulogne-Billancourt, France; 33-1-4761-7689; fax 33-1-4761-7465; e-mail alain.lecoroller@wanadoo.fr; http://wa157.lerelaisinternet.com/cme-emulsion.

**25-29** Conf. on Fluid Particle Interactions, *Barga, Italy*. United Engineering Foundation, 3 Park Ave., New York, NY 10016-5902; 212-591-7836; fax 212-591-7441; e-mail engfnd@aol.com; www.uefoundation.org.

**25-30** 11th Intl. Conf. on Rapidly Quenched and Metastable Materials, *Oxford, UK*. P. Schumacher, Dept. of Materials, Oxford Univ., Parks Rd., Oxford OX1 3PH, UK; 44-1234-378862; fax 44-1234-376219; e-mail rq11@materials.ox.ac.uk; www.materials.ox.ac.uk/rq11.

**28-31** 2nd Intl. Mould & Die Making and Manufacturing Technology Exhibition for Asia, *Hong Kong*. Business and Industrial Trade Fairs Ltd., Unit 1223, HITEC, 1 Trademart Dr., Kowloon Bay, Hong Kong; 852-2865-2633; fax 852-2866-1770; e-mail enquiry@bitf.com.hk.

## SEPTEMBER 2002

**4-6** 35th Intl. Symposium on Microelectronics, *Denver, CO*. Intl. Microelectronics And Packaging Society, 611 2nd St. NE, Washington, DC 20002; 202-548-4001; fax 202-548-6115; www.imaps.org.

**8-12** 6th Intl. Meeting on Magnetic Resonance in Porous Media, *Ulm, Germany*. www.uni-ulm.de/nmr/mrpm6/early\_notification.htm.

**9-13** 8th Intl. Conf. on Plasma and Surface Engineering, *Garmisch-Partenkirchen, Germany*. Arbeitskreis Plasmaoberflächentechnologie (PISE Germany), c/o K. Reichel, VDI-Technologiezentrum, Graf-Redcke-Str. 84, D-40239 Düsseldorf, Germany; 49-211-6214-567; fax 49-211-6214-484; e-mail akplasma@vdi.de; www.akplasma.org.

**10-12** Intl. Conf. on Design and Nature: Comparing Design in Nature with Science and Engineering, *Udine, Italy*. G. Cossutta, Conf. Secretariat, Wessex Inst. of Technology, Ashurst Lodge, Ashurst, Southampton SO40 7AA, UK; 44-238-029-3223; fax 44-238-029-2853; e-mail gcossutta@wessex.ac.uk; www.wessex.ac.uk.

**16-20** Intl. Conf. on Shot Peening, *Garmisch-Partenkirchen, Germany*. P. Schepp, Deutsche Gesellschaft für Materialkunde e.V., Hamburger Allee 26, D-60486 Frankfurt, Germany; 49-69-7917-750; fax 49-69-7917-733; e-mail shot-peening@dgm.de; www.dgm.de/shot-peening.

**17-20** Materials Science Forum on Materials Science for Future Sustainable Technologies, *Augsburg, Germany*. e-mail stritzker@physik.uni-augsburg.de.

**22-26** 3rd World Congress on Microwave and Radio Frequency Processing, *Sydney, Australia*. e-mail mrf2002@tourhosts.com.au; www.microwave-rf.org.

**24-27** 3rd World Congress on Emulsions, *Lyon, France*. CME, 50 Place Marcel Pagnol, 92100 Boulogne-Billancourt, France; 33-147-617-689; fax 33-147-617-465; e-mail alain.lecoroller@wanadoo.fr; www.cme-emulsion.com.

**24-28** 7th Intl. Conf. on Semi-Solid Processing of Alloys and Composites, *Tsukuba, Japan*. M. Kiuchi, 7th S2P Secretariat, KIL-AMETEC, Rm. 703, 5-30-1 Shiba, Minato-ku, Tokyo 108-0014, Japan; fax 81-3-5730-3136; e-mail s2p7@jstp.or.jp; www.s2p7@jstp.or.jp.

## OCTOBER 2002

**1-4** 54th Pacific Coast Regional and ACerS Basic Science Div. Meeting, *Seattle, WA*. American Ceramic Society, P.O. Box 6136, Westerville, OH 43086-6136; 614-890-4700; fax 619-899-6109; e-mail customersvc@acers.org; www.ceramics.org.

**6-10** TMS Fall Meeting, *Columbus, OH*. TMS Programming Dept., 184 Thorn Hill Rd., Warrendale, PA 15086; 724-776-9000; fax 724-776-3770; e-mail ckobert@tms.org; www.tms.org.

**7-10** 7th Spanish Natl. Materials Conf., *Madrid, Spain*. O. Sanz, Sociedad Espanola de Ceramica y Vidrio; 34-918-711-800; fax 34-918-700-500; www.secv.es/madridmateriales2002.

**12-15** ACerS Glass and Optical Materials Div. Meeting, *Pittsburgh, PA*. American Ceramic Society, P.O. Box 6136, Westerville, OH 43086-6136; 614-890-4700; fax 619-899-6109; e-mail customersvc@acers.org; www.ceramics.org.

**20-25** 202nd Meeting of the Electrochemical Society, *Salt Lake City, UT*. The Electrochemical Society, 65 S. Main St., Pennington, NJ 08534-2839; 609-737-1902; fax 609-737-2743; e-mail ecs@electrochem.org; www.electrochem.org.

24-26 ▼ 2nd Intl. Conf. on Shaping of Advanced Ceramics, *Ghent, Belgium*. 32-14-335607; e-mail greet.meyen@vito.be.

29-3 ABET Annual Meeting, *Pittsburgh, PA*. 2002 ABET Annual Meeting, 11 Market Place, Ste. 1050, Baltimore, MD 21202-4012; www.abet.org.

NOVEMBER 2002

11-15 44th Annual Meeting of the APS Division of Plasma Physics, *Orlando, FL*. American Physical Society, One Physics Ellipse, College Park, MD 20740-3844; 301-209-3200; fax 301-209-0865; e-mail meetings@aps.org; www.aps.org.

DECEMBER 2002

2-6 MRS Fall Meeting, *Boston, MA*. Materials Research Society, 506 Keystone Dr., Warrendale, PA 15086-7573; 724-779-3003; fax 724-779-8313; e-mail info@mrs.org; www.mrs.org. **MRS.**

7-11 EUCHEM Conf. on Molecular Tribology, *Märsta, Sweden*. Molecular Tribology, The Swedish Natl. Committee for Chemistry, Wallingatan 24 3tr, SE-111 24 Stockholm, Sweden; 46-8-411-52-60; fax 46-8-10-66-78; e-mail anna@chemsoc.se; www.chemsoc.se.

MARCH 2003

2-6 TMS Annual Meeting, *San Diego, CA*. Programming Dept., The Minerals, Metals & Materials Society, 184 Thorn Hill Rd., Warrendale, PA 15086; 724-776-900; fax 724-776-3770; e-mail ckobert@tms.org.

APRIL 2003

21-25 ▼ MRS Spring Meeting, *San Francisco, CA*. Materials Research Society, 506 Keystone Dr., Warrendale, PA 15086-7573; 724-779-3003; fax 724-779-8313; e-mail info@mrs.org; www.mrs.org. **MRS.**

JUNE 2003

9-13 ▼ E-MRS Spring Meeting, *Strasbourg, France*. E-MRS, 23 rue du Loess, B.P. 20, 67037 Strasbourg Cedex 02, France; 33-3-8810-6372; fax 33-3-8810-6343; e-mail emrs@phase.c-strasbourg.fr; www.emrs.c-strasbourg.fr. **E-MRS.**

29-4 ▼ 16th Intl. Conf. on Ion Beam Analysis, *Albuquerque, NM*. B. Doyle, Sandia Natl. Laboratories, P.O. Box 5800, Albuquerque, NM 87185; 505-844-7568; fax 505-844-7775; e-mail bidoyle@sandia.gov.

JULY 2003

10-14 ▼ Thermec 2003 Intl. Conf., *Madrid, Spain*. T. Chandra, Faculty of Engineering, Univ. of Wollongong, Wollongong 2522, Australia; 61-242-213-008; fax 61-242-214-921.

AUGUST 2003

31-5 ▼ 16th Intl. Mass Spectrometry Society Conf., *Edinburgh, Scotland*. A. Upton, Secretary to the 16th IMSC Organizing Committee, Orchard House, 172 High Street Yelling, St. Neots, PE19 6SD, UK; 44-1480-88-0069; fax 44-1480-88-059; e-mail imscEdinburgh@btinternet.com; www.imsc-edinburgh2003.com.

DECEMBER 2003

1-5 ▼ MRS Fall Meeting, *Boston, MA*. Materials Research Society, 506 Keystone Dr., Warrendale, PA 15086-7573; 724-779-3003; fax 724-779-8313; e-mail info@mrs.org; www.mrs.org. **MRS.**


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